

UNIT -I**REVIEW OF MICROELECTRONICS AND INTRODUCTION TO MOS TECHNOLOGIES**

1. a) Explain different steps involved in preparation CMOS using twin tub process. [7M]
b) Define Figure of merit and g_{ds} . [3M]
2. Derive the relation between drain to source current I_{ds} VS drain to source voltage V_{ds} in non-saturated and saturated region. [10M]
3. a) Compare CMOS and Bi-CMOS. [6M]
b) Write short notes on latch-up in CMOS circuits [4M]
4. Determine the Pull-up and Pull-down ratio of for NMOS inverter through one (or) more pass transistors. [10M]
5. (a) What is meant by body effect? [5M]
(b) Explain a Bi-CMOS inverter with a neat sketch. [5M]
6. a) Define the term Threshold voltage of MOSFET and explain its significance. [5M]
b) Briefly discuss about the pass transistor [5M]
7. a) Compare NMOS and CMOS technology. [5M]
b) Derive the expression for ZPU/ZPD. [5M]
8. a) Illustrate the main steps in a typical N-WELL process. [7M]
b) Explain the NMOS depletion mode transistor. [3M]
9. a) Explain about the Structure of NMOS transistor. [7M]
b) Explain the operation of CMOS inverter with a logic diagram [3M]
10. a) Explain about PASS transistor with neat sketch [5M]
b) Define electrical properties of MOS circuits. [5M]

Prepared by: A.VENU

UNIT -II**LAYOUT DESIGN AND TOOLS\LOGIC GATES & LAYOUTS**

1. a) Explain how stick diagrams can be used for layout diagrams. [7M]
b) Discuss the wiring capacitances [5M]
2. (a) Explain about static complementary gates. [5M]
(b) What are the different strategies for building low power gates? Explain. [5M]
3. (a) Differentiate switch logic and gate logic. [5M]
(b) List the salient features of subsystem layout. [5M]
4. (a) Explain clearly the Scalable design rules. [5M]
(b) Explain clearly Wires and Vias in VLSI design. [5M]
5. Design the static complementary pull-up and pull-down networks for the logic expression: $f(A, B, C, D) = (A+B)(C+D)$ [10M]
6. a) Explain switch Logic and Alternative Logic. [6M]
b) Briefly discuss about the combinational logic functions [4M]
7. a) Explain briefly about Resistive Inter-Connect delay and RC Trees delay. [5M]
b) Explain about driving large loads with diagram. [5M]
8. What are layout design rules? Explain the layer representations and based design rules for CMOS process. [10M]
9. (a) Implement NAND gate in NMOS technology and hence draw its stick diagram and design a layout for the stick diagram. [5M]
(b) Discuss about the effects of scaling down the dimensions of MOS circuits and Systems. [5M]
10. Define the following terms
 - (a) Speed power product. [5M]
 - (b) Delay through RC transition time [5M]

Prepared by: **Mr.A.VENU**

UNIT -III**COMBINATIONAL LOGIC NETWORKS\SEQUENTIAL SYSTEMS**

1. a) Explain in detail about the requirements in designing logic networks using realistic interconnect models. [7M]
b) Draw the single row layout design. [3M]
2. a) Explain briefly about power optimization. [5M]
b) Draw the switch implementation of a multiplier. [5M]
3. (a) What are the various simulators used for combinational logic? [5M]
(b) Write short notes on power optimization of combinational logic networks. [5M]
4. a) Briefly discuss about Fanout with diagram [5M]
b) Explain path delay with respect to combination networks delay. [5M]
5. a) Explain the clocking disciplines and power optimization in sequential systems. [5M]
b) Briefly discuss about crosstalk minimization. [5M]
6. (a) Explain clearly about switch simulation. [5M]
(b) Explain about the combinational network testing. [5M]
7. Draw the layout diagram of three input NAND gate in CMOS. [10M]
8. What is simulation? Explain about various types of simulation applied at different levels of fabrication. [10M]
9. a) With suitable examples explain about network delays combinational logic circuits. [5M]
(b) Implement an 'n-bit' shift register and explain its operation over one clock cycle. [5M]
10. a) Discuss briefly about standard cell layout design. [5M]
b) Briefly explain the block diagram of phase locked loop for clock generation. [5M]

Prepared by: **Mr.A.VENU**

UNIT-IV**FLOOR PLANNING AND ARCHITECTURE DESIGN**

- 1 a) Briefly discuss about floor planning methods. [5M]
b) Draw and explain the block placement and channel definition. [5M]
- 2 a) Write a short notes on global routing [5M]
b) Explain the concept of switch box routing [5M]
- 3 a) Discuss about different floor planning tips. [5M]
b) Write a short notes on design validation. [5M]
- 4 a) Explain about placement and routing at chip level design. [5M]
b) Explain about architecture testing. [5M]
- 5 a) Discuss about off-chip connections and packages [7M]
b) Draw and explain the power line inductance [3M]
- 6 a) Draw and explain the I/O architecture with a neat sketch. [5M]
b) Explain the concept of pad design with a diagram. [5M]
- 7 Explain the concept of register transfer design with data path control architecture. [10M]
- 8 With a flow chart explain the concept of ASM chart design. [10M]
- 9 a) Discuss high level synthesis. [5M]
b) Write a short notes on power down modes. [5M]
- 10 a) Explain the architecture for low power with a diagram. [5M]
b) Write a notes on linear feedback shift register. [5M]

Prepared by: **Mr.A.VENU**

UNIT-V**INTRODUCTION TO CAD SYSTEM AND CHIP DESIGN**

- 1 Write about the following
 - a)Hardware-software co-design [5M]
 - b)Floor planning methods [5M]
- 2
 - a)Write a short notes on layout synthesis [5M]
 - b)Discuss about global routing [5M]
- 3
 - a)With an example give the method involved in the chip design. [7M]
 - b)Briefly discuss about CAD system. [3M]
- 4
 - a)Explain about system on chips and embedded CPUs. [5M]
 - b)Write a notes on logic synthesis. [5M]
- 5 With a diagram explain about detailed routing method. [10M]
- 6
 - a)Explain the timing analysis and optimization process [5M]
 - b)Write about test generation pattern. [5M]
- 7
 - a)Explain the technology independent logic optimization. [7M]
 - b)Draw the diagram of irredundant-reduced cycle. [3M]
- 8
 - a)Write a short notes on sequential machine optimizations. [5M]
 - b)Explain about scheduling ad binding. [5M]
- 9
 - a)Write about switch level simulation [7M]
 - b)Write a short notes on chip level placement. [3M]
- 10 Explain about technology dependent logic optimization. [10M]

Prepared by: **Mr.A.VENU**